

Ventiva Appoints Barry O'Connell Vice President of Reliability and Quality To Drive and Optimize Next Stage of Mass Adoption

Fremont, Calif.—May 23, 2024—Ventiva®, a leading company in active cooling solutions for electronic devices, today announced the appointment of Barry O'Connell as Vice President of Reliability and Quality. In this role, O'Connell will leverage more than 20 years of experience in reliability and quality improvement initiatives to optimize Ventiva's proprietary Ionic Cooling Engine (ICE®) air movement technology for mass market success.

"Barry is a deeply experienced and thoughtful engineering executive, and we are pleased that he joined Ventiva in this critical role," said Carl Schlachte, CEO, Chairman, and Director of Ventiva. "He brings the expertise needed to ensure we deliver exceptional value to our customers who use our ICE® technology in their products."

Before joining Ventiva, O'Connell held senior roles in reliability and quality management in various industries, including semiconductors, microelectromechanical systems (MEMs), and photonics.

Most recently, O'Connell served as Vice President of Quality and Reliability at Rockley Photonics where his contributions were pivotal in establishing critical-to-quality parameters to ensure sensor performance. He also spearheaded quality initiatives for MEMs at TDK InvenSense, and, at Fairchild Semiconductor, significantly improved the first-pass new product introduction success rate to more than 95% by enhancing technology reliability development. His leadership at National Semiconductor led to the implementation of advanced processes, such as device safe operating area (SOA) for transistors and championing built-in-reliability for integrated circuits. O'Connell began his career at Tyndall Research Center where he developed the sensitive radiation dosimeter RADFET to use in space and ground radiative environments.



About Ventiva

<u>Ventiva®</u>, a leading company in active cooling solutions for electronic devices, enables thinner, faster, and cooler high-performance devices that are lightweight, silent, and vibration-free. The company's patented ICE® technology is a pioneering all-electronic heat transfer technology created to address the thermal problems exacerbated by modern high-performance semiconductor design. © 2024. Ventiva, Inc. All rights reserved. Ventiva and ICE are registered trademarks and trademarks of Ventiva, Inc., in the U.S. and other countries. All other trademarks belong to their respective owners.